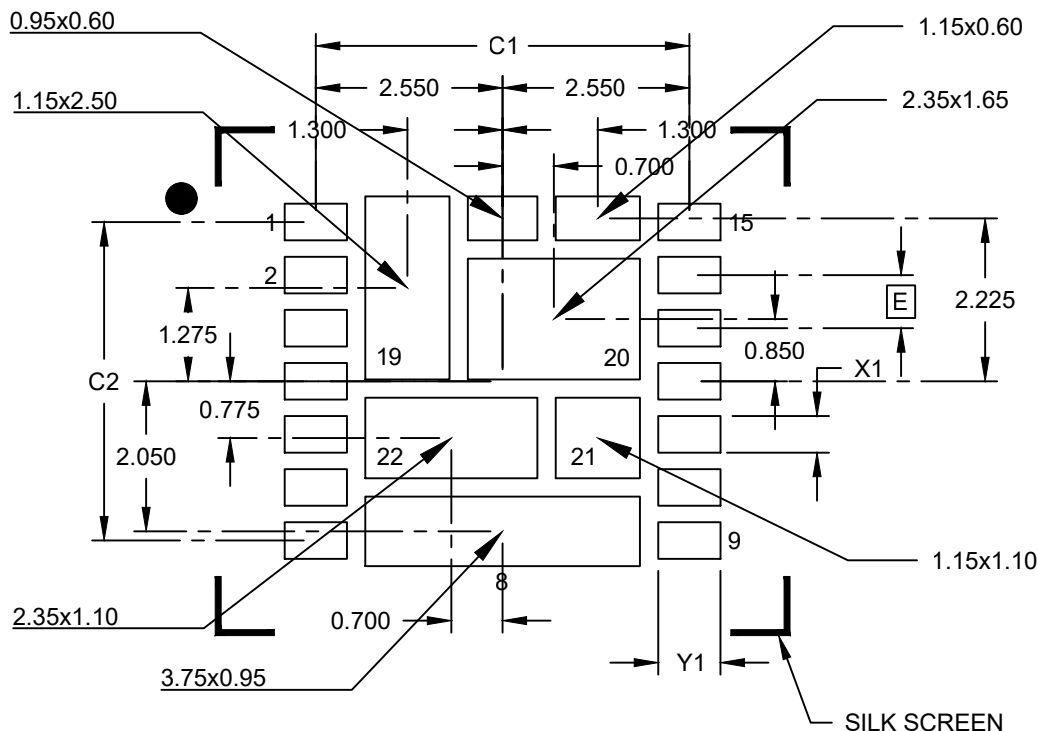


22-Lead Land Grid Array 5.8x4.9x1.71mm (8FW) [LGA] - System in Package [SIP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E	0.725 BSC		
Contact Pad Spacing	C1		5.10	
Contact Pad Spacing	C2		4.35	
Contact Pad Width (X14)	X1			0.50
Contact Pad Length (X14)	Y1			0.85

Notes:

- Dimensioning and tolerancing per ASME Y14.5M
BSC: Basic Dimension. Theoretically exact value shown without tolerances.
- For best soldering results, please refer to current industry standard IPC-7093.